

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: JAE SUK LEE

Application No.:

Confirmation
No:

Filed: December 10, 2003

Group No.:
Examiner

For: BARRIER STRUCTURE FOR COPPER METALLIZATION AND METHOD FOR THE
MANUFACTURE THEREOF

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

APPLICATION DATA SHEET
37 C.F.R. § 1.76

BIBLIOGRAPHIC DATA

1. Applicant information

First applicant: JAE SUK LEE
Citizenship: Republic of Korea
Residence: Seoul, Korea

2. Correspondence information

Correspondence for this application should be addressed as follows:

Customer No.: 00909

3. Application information

Title of Invention: BARRIER STRUCTURE FOR COPPER METALLIZATION AND
METHOD FOR THE MANUFACTURE THEREOF

Docket number assigned to this application: 021906-0306952

Suggested Classification: Class:

Subclass:

Technology Center to which subject matter is assigned:

Total number of drawing sheets: 2

Type of application:

Utility

Application is to be published. Suggested drawing figure for publication:

Secrecy order under § 5.2:

This application does not disclose subject matter of an application which is under a secrecy order pursuant to § 5.2.

4. Representative information

The following have a power of attorney or authorization of agent in this application:

Customer No.: 00909

5. Foreign priority information

Foreign priority is claimed for this application as follows:

Country: Republic of Korea
Application No.: 10-2002-0086358
Filing Date: December 30, 2002
Status: pending


6. Assignee information

The assignee(s) of this application is/are:

Dongbu Electronics Co., Ltd.
891-10, Daechi-dong, Gangnam-gu
Seoul,
Korea
Extent of interest of assignee in application: 100%

Date: December 10, 2003

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Signature of Practitioner
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